

ABSTRACT

Pb-free soldering alloy that does not include any amount of Pb is proposed.

5 The soldering alloy prevents Cu comprised in a printed-circuit board from combining Ni comprised in the soldering alloy at the soldered part, that is, prevents Cu from being precipitated and diffused in the soldering alloy sufficiently, suppresses the generation of fine cracks at the soldered part
10 and raises the mechanical strength of the soldered part.

 The Pb-free soldering alloy is characterized in that it comprises Ag of 3.5 to 6.0 wt.%, Ni of 0.001 to 1.0 wt.% and Sn of the balance.

15

20



25